

Adhesive that can be bonded to Al foil

TOYAL Conductive Adhesive

TCB Series

< Features >

- ▶ Excellent conductivity and adhesion on etched Al circuit

- ▶ Low deterioration of adhesive on etched Al circuit in high temperature and high humidity environment

- ▶ Ag-plated filler is used. Cost saver over 100% Ag fillers

DATA

Cured adhesive comparison

Evaluation	Evaluation methods	TCB series	Conventinal Ag adhesive
Resistance	Four-probe method	$5.5 \times 10^{-4} \Omega \cdot \text{cm}$	$3.0 \times 10^{-4} \Omega \cdot \text{cm}$
Migration resistance	L/S=300 μm 85°C/85% 50V	above 500hr.	under 10hr.
Pull strength (for Al)	JIS K6850	0hr.	6.4N/mm ²
		After 500hr.	0.5N/mm ²
Interface resistance (for Al)	Our measurement method	0hr.	0.5 Ω
		After 500hr.	Out of range

Condition

Viscosity(@2.5rpm 25°C)	50~70Pa · s
Curing conditions	150°C/30分
Appearance	Brown paste
Storage method	Freezing

